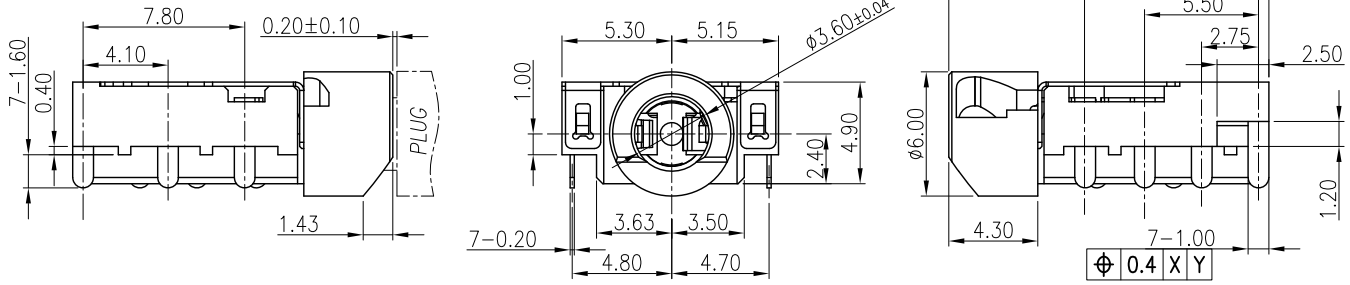
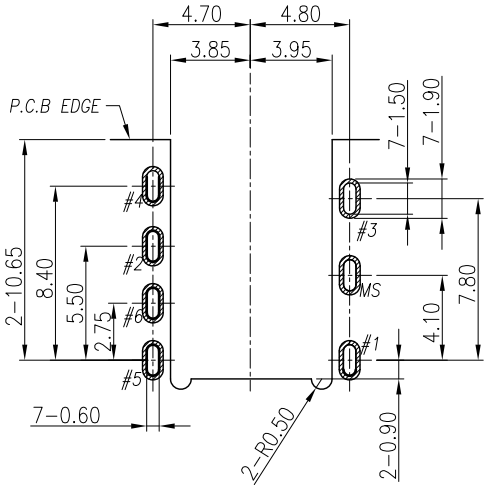
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO.: T130506-2A	HM-JIANG	2013.07.10



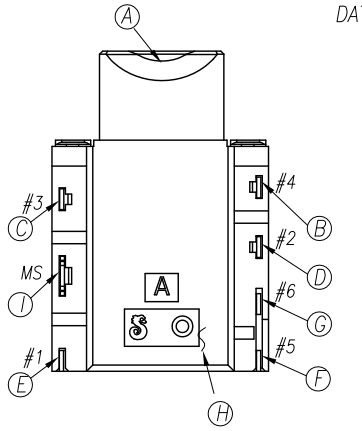
SPECIFICATIONS:

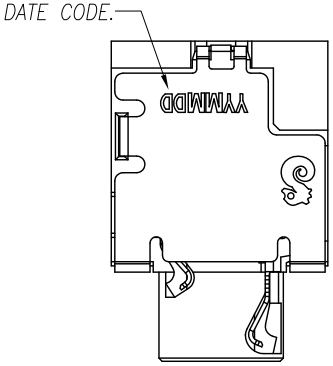
1. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC .
2. CONTACT RESISTANCE: 50mΩ MAX.(INITIAL).
3. INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
4. UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
5. LIFE TEST: 5,000 CYCLES.
6. INSERTION FORCE: INITIAL 0.3-3.0Kgf ,
7. WITHDRAWAL FORCE: INITIAL 0.3-3.0 Kgf,
8. AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
9. AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
10. MARKING: MARK "S" ON TOP OF CONNECTOR.
11. PACKING : TAPE & REEL.
12. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
13. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
14. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:

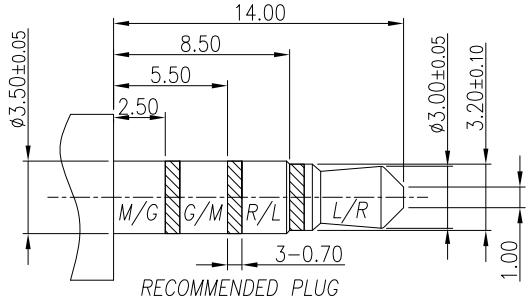


RECOMMENDED PCB LAYOUT

TOP VIEW : TOL.±0.05



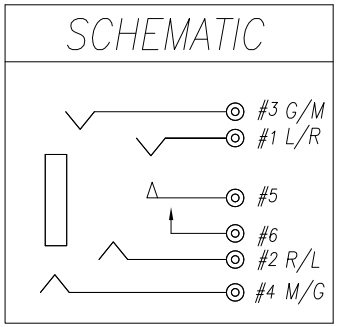




RECOMMENDED PLUG

ø3.5 4-POLE STANDARD PLUG

SCHEMATIC



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
I	SHELL	1	COPPER ALLOY, 0.2t	Ni 60u" Min.
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER NI 50u".
F	TRANSFER	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; Matte-Tin 80u" ON SOLDER AREA; ALL OVER NI 50u".
E	TIP	1	COPPER ALLOY, 0.2t	
D	RING-A	1	COPPER ALLOY, 0.2t	
C	RING-B	1	COPPER ALLOY, 0.2t	
B	EARTH	1	COPPER ALLOY, 0.2t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.5 X.X :±0.3 X.XX :±0.2

ANGLES: X :±2° X.X :±1°

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5ø PHONE JACK		
DWN	HM-JIANG	PART NO. 2SJ3080-031111F	
CHKD	BRUCE	SCALE 4:1	UNIT: mm
APVD	LUSSEN	SIZE: A3	SHEET:1 OF 1 REV: A

CUSTOMER COPY

文件編號 RD-06-043-A